RF Micro Devices
RF6260
Power Amplifier Module from the Samsung Galaxy S II™ Smartphone

Package Analysis
RF Micro Devices RF6260
Power Amplifier Module
Package Analysis

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Chipworks
3685 Richmond Road, Suite 500
Ottawa, Ontario  K2H 5B7  Canada
T 1-613-829-0414
F 1-613-829-0515
Web site: www.chipworks.com
Email: info@chipworks.com

Please send any feedback to feedback@chipworks.com